## 1. Part No. Expression:

# <u>SPS252012ER47MF</u>

- (a)
- (b)
- (c) (d) (e) (f)
- (a) Series code

(d) Inductance code

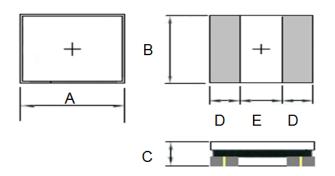
(b) Dimension code

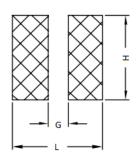
(e) Tolerance Code

(c) Material code

(f) RoHS Compliant

# 2. Configuration & Dimensions : (Unit: mm)





Recommended PCB Pattern

Unit: mm

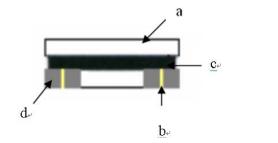
| Α             | В               | С        | D         | E         | G    | Н    | L    |
|---------------|-----------------|----------|-----------|-----------|------|------|------|
| 2.5 -0.1/+0.2 | 2.0 -0.05/+0.35 | 1.2 Max. | 0.85 Ref. | 0.80 Ref. | 0.80 | 2.40 | 2.90 |

# 3. Schematic





### 4. Material List



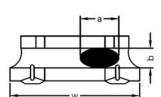
Exposed wire tolerance limit of coating resin part on product side:

1. Width direction (dimension a): Acceptable when  $a \le w/2$ ;

Nonconforming when a > w/2

a) Coreb) Wirec) Glued)Terminal

- 2. Length direction (dimension b): Dimension b is not specified
- The total area of exposed wire occurring to each sides is not greater than 50% of coating resin area and is acceptable



# 5. General Specification

- a) Isat: Based on inductance change (ΔL/Lo: ≤30% Typ.)
- b) Irms: Based on temperature rise (ΔT: 40°C Max.)
- c) Operating Temperature: 40°C to +125°C (including self-temperature rise)
- d) Storage Temperature: 40°C to +125°C
- e) Storage Condition (component in its packaging)

i) Temperature: Less than 40°C

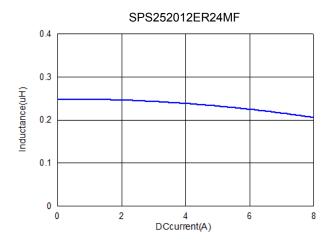
ii) Humidity: 60% RH

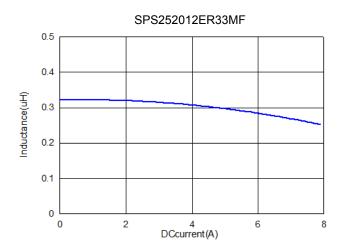
## 6. Electrical Characteristics

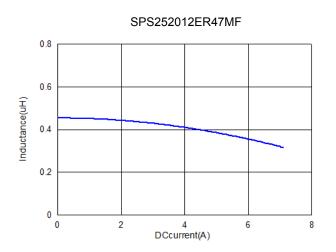
| Part No.        | Inductance (μH) | Test Frequency (Hz) | DCR<br>(Ω) Max. | Isat<br>(A) Max. | Irms<br>(A) Typ. |
|-----------------|-----------------|---------------------|-----------------|------------------|------------------|
| SPS252012ER24MF | 0.24 ± 20%      | 0.1V/1M             | 0.028           | 6.50             | 4.70             |
| SPS252012ER33MF | 0.33 ± 20%      | 0.1V/1M             | 0.032           | 4.60             | 4.50             |
| SPS252012ER47MF | 0.47 ± 20%      | 0.1V/1M             | 0.032           | 4.50             | 4.40             |
| SPS252012ER68MF | 0.68 ± 20%      | 0.1V/1M             | 0.043           | 3.80             | 3.60             |
| SPS252012E1R0MF | 1.00 ± 20%      | 0.1V/1M             | 0.057           | 3.40             | 3.50             |
| SPS252012E1R5MF | 1.50 ± 20%      | 0.1V/1M             | 0.096           | 2.60             | 2.50             |
| SPS252012E2R2MF | 2.20 ± 20%      | 0.1V/1M             | 0.102           | 2.30             | 2.30             |

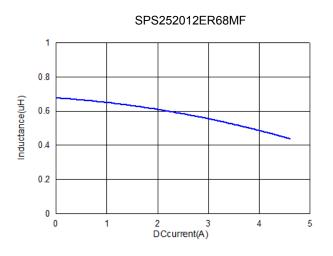


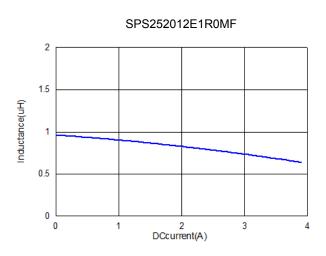
# 7. Characteristics Curves

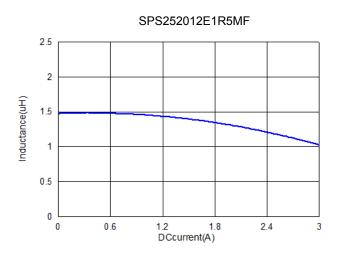




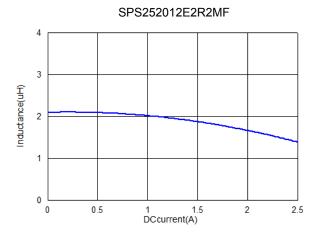












## 8. Soldering

Mildly activated rosin fluxes are preferred. The terminations are suitable for all wave and re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

#### 8-1 Solder Re-flow:

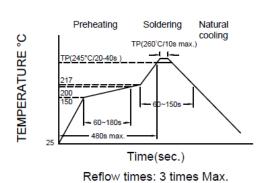
Recommended temperature profiles for re-flow soldering in Figure 1.

## 8-2 Soldering Iron (Figure 2):

Products attachment with soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

#### Note:

- a) Preheat circuit and products to 150°C.
- b) 355°C tip temperature (Max.)
- c) Never contact the ceramic with the iron tip
- d) 1.0mm tip diameter ( Max.)
- e) Use a 20 watt soldering iron with tip diameter of 1.0mm
- f) Limit soldering time to 4~5 secs.



Preheating Soldering Natural cooling

350

Over 60s

Time(sec.)

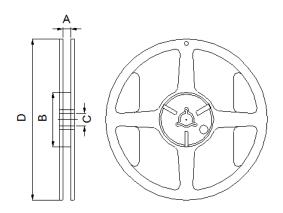
Iron Soldering times: 1 times Max.

Fig.1 Fig.2



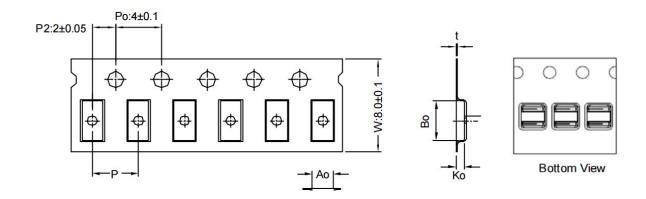
# 9. Packaging Information

#### 9-1. Reel Dimension



| Туре     | A (mm)    | B (mm)  | C (mm)     | D (mm)     |
|----------|-----------|---------|------------|------------|
| 7" x 8mm | 8.4 ± 1.0 | 50 Min. | 13.0 ± 0.8 | 178.0± 2.0 |

## 9-2. Tape Dimension



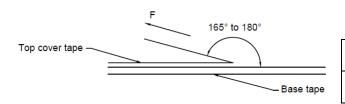
| Series    | Ao(mm)    | Bo(mm)    | Ko(mm)    | P(mm)     | t(mm)     |
|-----------|-----------|-----------|-----------|-----------|-----------|
| SPS252012 | 2.45±0.10 | 2.85±0.10 | 1.40±0.10 | 4.00±0.10 | 0.23±0.05 |

# 9-3. Packaging Quantity

| Size       | 252012 |  |
|------------|--------|--|
| Chip/ Reel | 2000   |  |



#### 9-4. Tearing Off Force



The force for tearing off cover tape is 15 to 80 grams in the arrow direction under the following conditions.

| Room Temp | Room         | Room atm   | Tearing Speed (mm/min) |
|-----------|--------------|------------|------------------------|
| (°C)      | Humidity (%) | (hPa)      |                        |
| 5 - 35    | 45 - 85      | 860 - 1060 | 300                    |

# **Application Notice:**

1. Storage Conditions:

To maintain the solderability of terminal electrodes:

- a) Recommended products should be used within 12 months from the time of delivery.
- b) The packaging material should be kept where no chlorine or sulfur exists in the air.

#### 2. Transportation:

- a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- b) Vacuum pick up is strongly recommended for individual components.
- c) Bulk handling should ensure that abrasion and mechanical shock are minimized.